



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



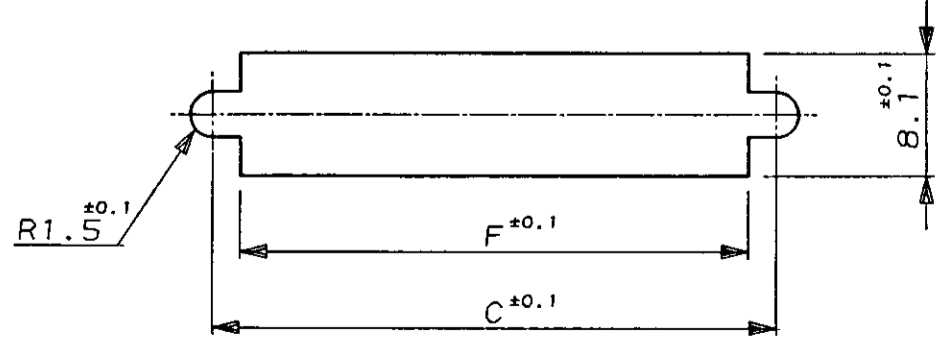
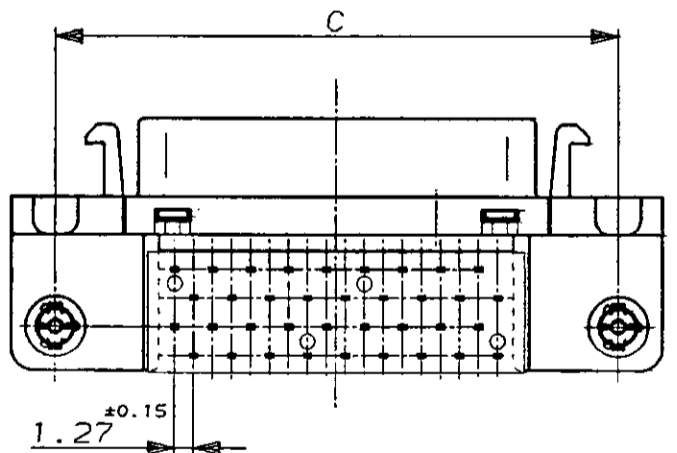
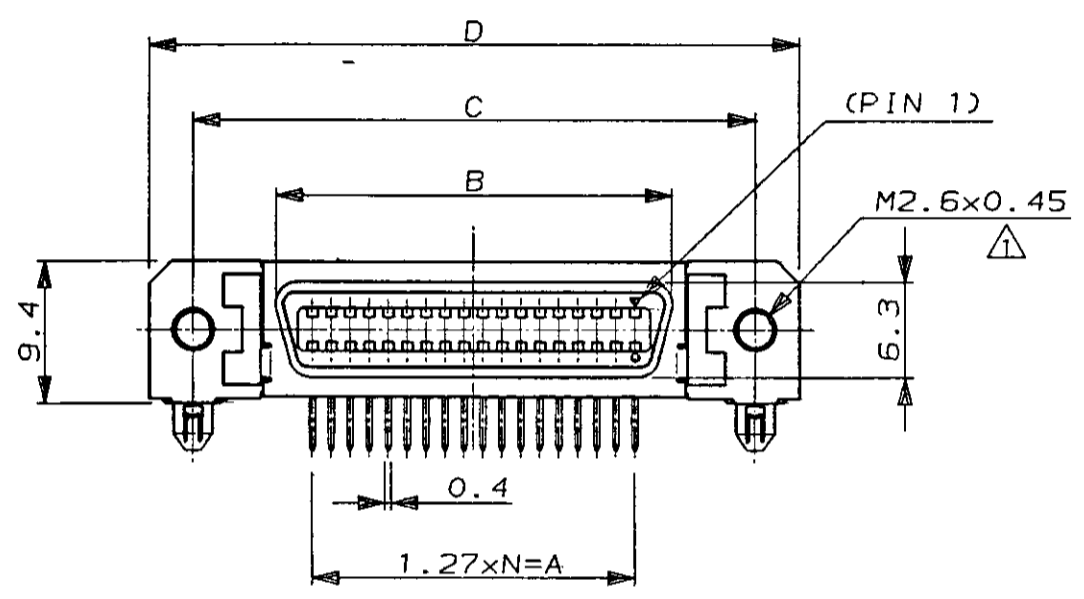
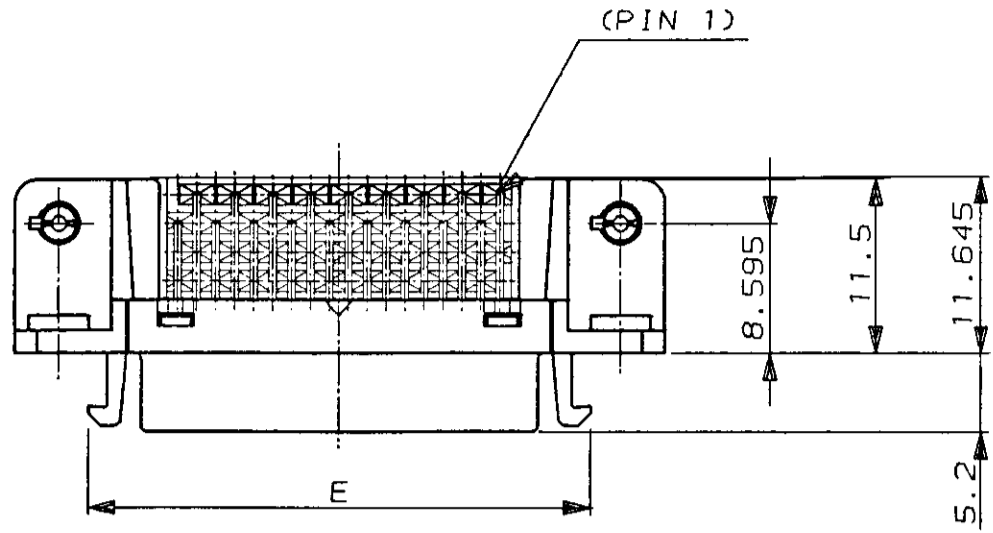
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

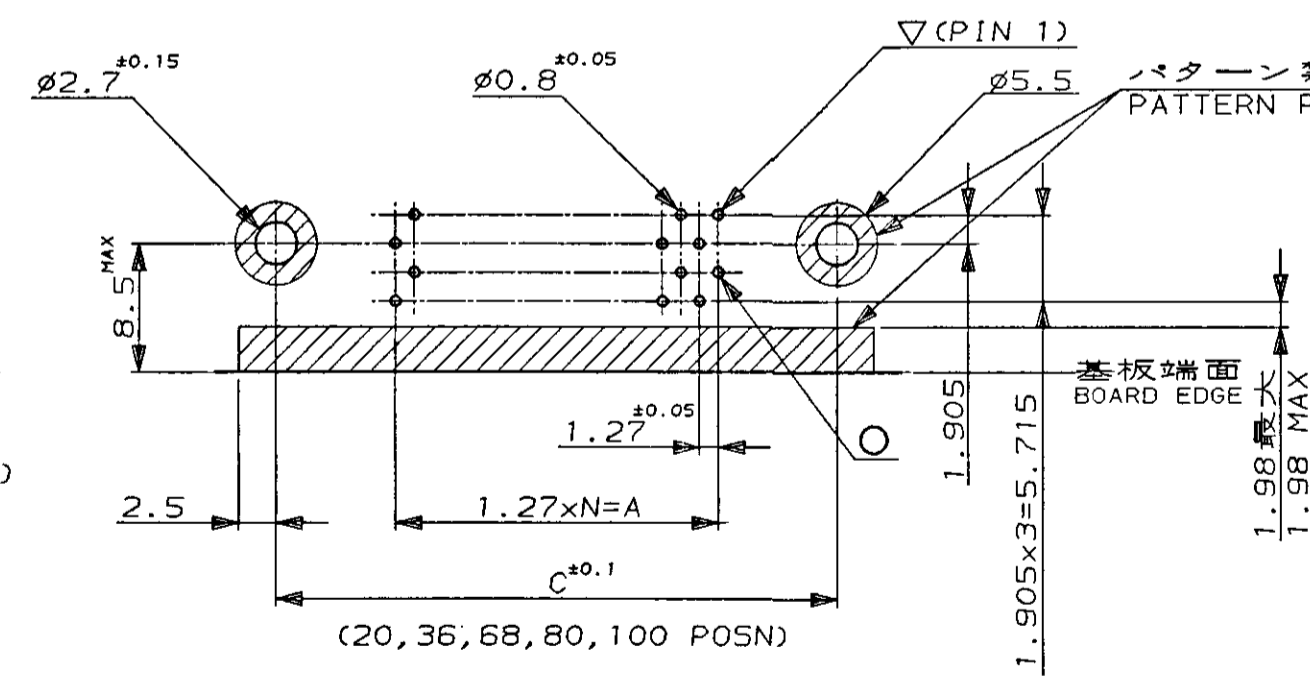
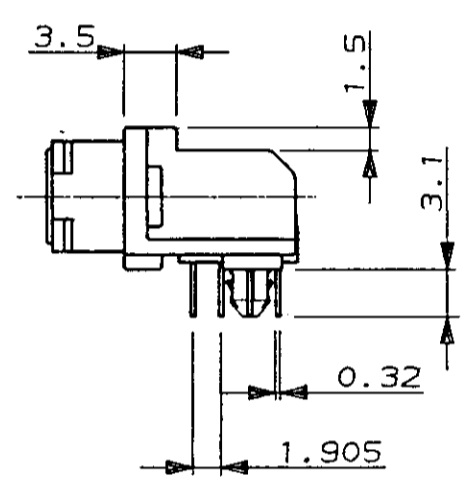
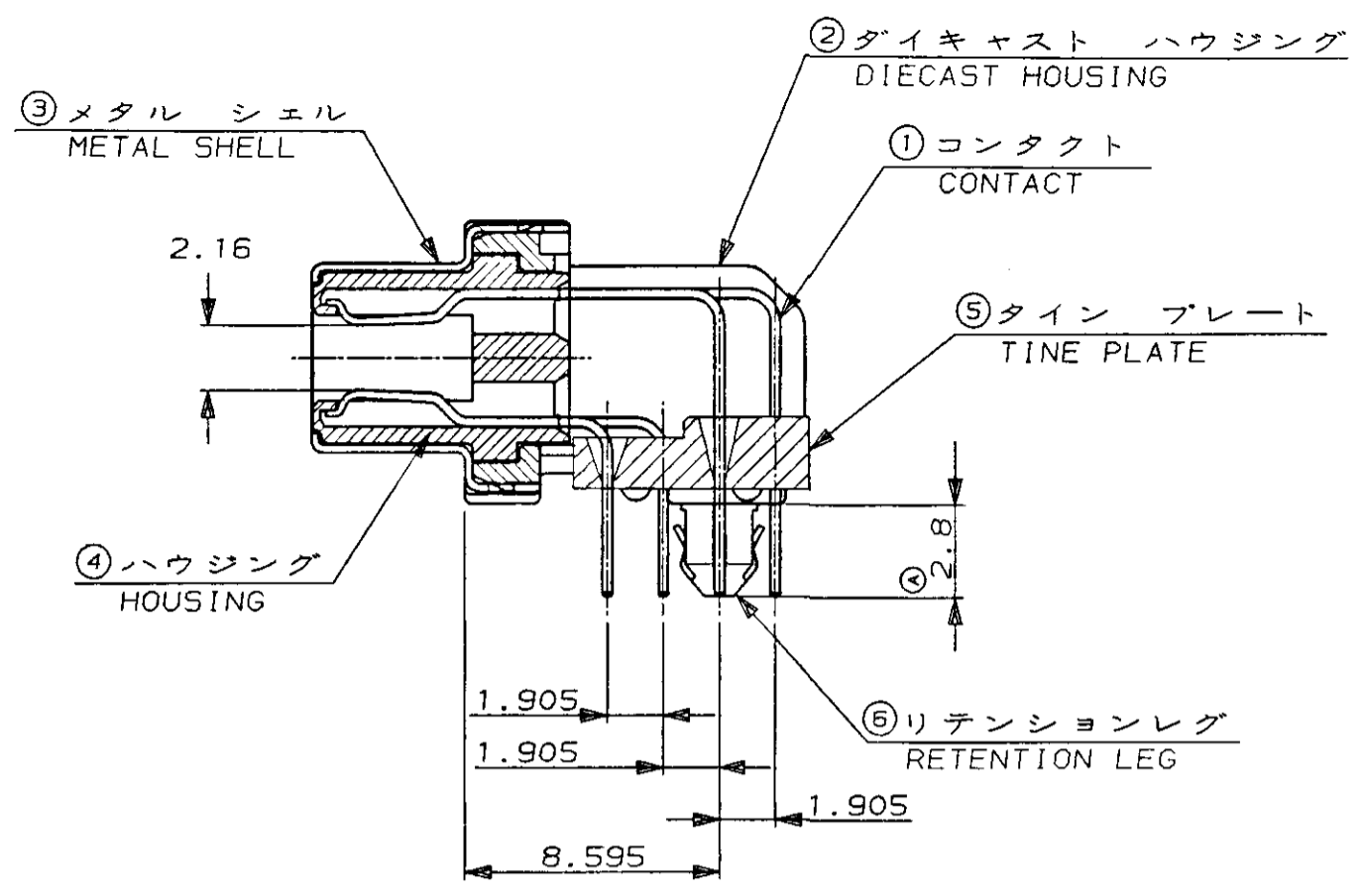
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





推奨パネルカット寸法  
RECOMMENDED PANEL CUTOUT  
(厚さ2mm最大)  
THK; 2mm MAX



推奨基板穴あけ寸法  
RECOMMENDED PC BOARD  
MOUNTING DIMMENSION  
(14, 26, 50 POSN)  
(20, 36, 68, 80, 100 POSN)  
コネクタ取付面  
COMPONENT SIDE

ITEM	材 料 (MATERIAL)	仕 上 (FINISH)
①	銅合金 COPPER ALLOY	全面ニッケル下地めっき 接触部: 金めっき (0.3μ, 0.76μ以上) ティン部: 半田めっき NICKEL UNDER PLATE ALL OVER CONTACT AREA; Au (0.3μ, 0.76μ) SOLDER TINE AREA; TIN-LEAD PLATE
②	亜鉛ダイキャスト ZINC	ニッケルめっき NICKEL PLATING
③	鋼 t0.25 STEEL t0.25	銅下地めっき上にニッケルめっき NICKEL PLATE OVER COPPER UNDERPLATE
④	熱可塑性樹脂 (UL:94V-0)	色: 黒 COLOR; BLACK
⑤	THERMO-PLASTIC	
⑥	銅合金 COPPER ALLOY	ニッケル下地めっき上に半田めっき TIN-LEAD PLATE OVER NICKEL UNDERPLATE

NOTES

- RECOMMENDED SCREW SIZE; M2.6 PANHEAD SCREW (L=5)
- RECOMMENDED P.C BOARD THICKNESS; 1.6mm (REF.)
- CONNECTOR TO BE MATED; 175677
- INSERTION FORCE OF RETENTION LEG TO P.C.B; 2.2kg MAX/CONNECTOR.
- RETENTIVITY OF RETENTION LEG TO P.C.B; 0.5kg MIN/CONNECTOR.

注 記

- 適用ねじ: M2.6なべ小ねじ (L=5)
- 推奨基板厚: 1.6mm (参考)
- かん合相手コネクタ: 175677
- リテンションレグ挿入力 (対基板): 2.2kg MAX.
- リテンションレグ保持力 (対基板): 0.5kg MIN.

N	F	E	D	C	B	A	Au PLT.	POSITION	PART No.
39	61.9	61.55	71.45	65.55	54.53	49.53	0.76μm	80	3-178238-0
49	74.6	74.25	84.15	78.25	67.23	62.23	0.76μm	100	2-178238-9
33	54.2	53.93	63.83	57.93	46.91	41.91	0.76μm	68	2-178238-8
24	42.8	42.50	52.40	46.50	35.48	30.48	0.76μm	50	2-178238-7
17	33.9	33.61	43.51	37.61	26.59	21.59	0.76μm	36	2-178238-5
12	27.6	27.26	37.16	31.26	20.24	15.24	0.76μm	26	2-178238-4
9	23.8	23.45	33.35	27.45	16.43	11.43	0.76μm	20	2-178238-2
6	19.9	19.64	29.54	23.64	12.62	7.62	0.76μm	14	2-178238-1
39	61.9	61.55	71.45	65.55	54.53	49.53	0.3μm	80	1-178238-0
49	74.6	74.25	84.15	78.25	67.23	62.23	0.3μm	100	178238-9
33	54.2	53.93	63.83	57.93	46.91	41.91	0.3μm	68	178238-8
24	42.8	42.50	52.40	46.50	35.48	30.48	0.3μm	50	178238-7
17	33.9	33.61	43.51	37.61	26.59	21.59	0.3μm	36	178238-5
12	27.6	27.26	37.16	31.26	20.24	15.24	0.3μm	26	178238-4
9	23.8	23.45	33.35	27.45	16.43	11.43	0.3μm	20	178238-2
6	19.9	19.64	29.54	23.64	12.62	7.62	0.3μm	14	178238-1

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絶縁電線断面積 (WIRE AREA) mm² (AWG - ) 被覆外径 (INSULATION DIA.) mmφ 名称 (NAME) RECEPTACLE HDR ASS'Y (3.1mm) RETENTION LEG TYPE STANDARD CHAMP.050 Series (II)

材料 (MATERIAL) 仕上 (FINISH) 一般公差 (GENERAL TOLERANCE)

SEE TABLE SEE TABLE 10以下 ±0.2 100以下 ±0.25 300以下 ±0.3 角 度 ±3°

DR. 22/MAR/91 DE. H.KODAMA 尺 寸 (SCALE) 2-1 REV. C SHEET 1 OF 1

LTR 変更 (REVISION RECORD) DR. CHK. DATE Y.FUJIIURA APP. Y.FUJIIURA